

Amendments to the Specification:

Kindly amend the specification as follows:

Page 1, between the title and the heading "**BACKGROUND OF THE INVENTION**", insert

--CROSS REFERENCE TO RELATED APPLICATIONS

This is a divisional application of application Serial No. 09/788,664, filed February 21, 2001, which is hereby incorporated by reference in its entirety for all purposes.--

Please replace the paragraph beginning on page 1, line 18 with the following amended paragraph:

As seen in Fig. 6(B), inner electrodes 56a and 56b are formed on the mounting substrate 50, and each inner electrode 56a, 56b is connected to an outer electrode via through holes (not shown). These inner electrodes 56 are generally formed by electroplating. All of the inner electrodes 56 are electrically and physically connected to each other by interconnections ~~an interconnection~~ 58 and 59 before the mounting substrate 50 is diced along dicing line 62 into individual semiconductor devices. However, after dicing, the inner electrodes 56 should be electrically isolated from one another.

Please replace the paragraph beginning on pag 3, line 17 with the following amended paragraph:

Fig. 2(A)-(D) Figs. 2(A)-2(G) are process diagrams illustrating process steps employed in a method using a mounting substrate of the present invention[.];

Please replace the paragraph beginning on page 5, line 21 with the following amended paragraph:

Semiconductor chips 12 are fixed on mounting regions 20a-20d of a mounting substrate 10, respectively. Pads 14 of each semiconductor chip are connected to the inner electrodes 16 of a corresponding mounting region using bonding wire 15.
(Fig.2(A)) (Figs. 2(A) and 2(E)).

Please replace the paragraph beginning on page 6, line 2 with the following amended paragraph:

Then, each mounting block is filled with resin 30 as shown in Fig.2(B) Figs. 2(B) and 2(F). A dicing tape 32 is adhered on the surface of the molded resin 30. The mounting substrate 10 is diced into individual semiconductor devices 40. (Fig.2(C)) Figs. 2(C) and 2(G) Solder bumps 17 are then formed on outer electrodes of the mounting substrate. (Fig.2.(D)) (Fig. 2(D))

Please cancel the abstract, and replace the cancelled abstract with the enclosed new abstract:

A mounting substrate includes a substrate body having at least first and second adjacent chip mounting regions defined on a surface thereof, and further having a dicing line defined between the first and second mounting regions; a first plurality of inner electrodes aligned along a first side of the first chip mounting region[[,]]; a second plurality of inner electrodes aligned along a second side of the second chip mounting region, wherein the first side of the first chip mounting region confronts the second side of the second chip mounting region[[,]]; and an interconnect wiring pattern located between the first and second chip mounting ~~region~~ regions, and commonly connected to the first plurality of inner electrodes and the second plurality of inner electrodes, wherein the interconnect wiring pattern includes a plurality of connecting wiring portions[[,]] and ~~wherein~~ at least some of [[said]] the wiring pattern ~~extend~~ extends obliquely across the dicing line.